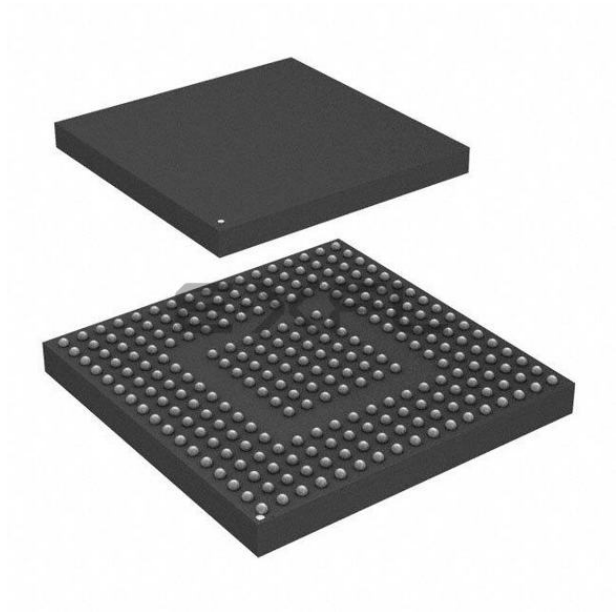

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z4
Core Size	32-Bit Dual-Core
Speed	120MHz
Connectivity	CANbus, FlexRay, LINbus, SPI, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 32x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	257-LFBGA
Supplier Device Package	257-LFBGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spc5643lf2mmm1

Table 1. MPC5643L device summary (continued)

Feature		MPC5643L
Packages	LQFP	144 pins
	MAPBGA	257 MAPBGA
Temperature	Temperature range (junction)	–40 to 150 °C
	Ambient temperature range using external ballast transistor (LQFP)	–40 to 125 °C
	Ambient temperature range using external ballast transistor (BGA)	–40 to 125 °C

1 The third eTimer (eTimer_2) is available with external I/O access only in the BGA package, on the LQFP package eTimer_2 is available internally only without any external I/O access.

2 The second FlexPWM module is available only in the BGA package.

1.4 Block diagram

Figure 1 shows a top-level block diagram of the MPC5643L device.

  - Individual programmable filters for each mailbox
  - 8 mailboxes configurable as a 6-entry receive FIFO
  - 8 programmable acceptance filters for receive FIFO
- Programmable clock source
  - System clock
  - Direct oscillator clock to avoid FMPLL jitter

1.5.27 FlexRay

The FlexRay module provides the following features:

- Full implementation of FlexRay Protocol Specification 2.1 Rev. A
- 64 configurable message buffers can be handled
- Dual channel or single channel mode of operation, each as fast as 10 Mbit/s data rate
- Message buffers configurable as transmit or receive
- Message buffer size configurable
- Message filtering for all message buffers based on Frame ID, cycle count, and message ID
- Programmable acceptance filters for receive FIFO
- Message buffer header, status, and payload data stored in system memory (SRAM)
- Internal FlexRay memories have error detection and correction

1.5.28 Serial communication interface module (LINFlexD)

The LINFlexD module (LINFlex with DMA support) on this device features the following:

- Supports LIN Master mode, LIN Slave mode and UART mode
- LIN state machine compliant to LIN1.3, 2.0, and 2.1 specifications
- Manages LIN frame transmission and reception without CPU intervention
- LIN features
  - Autonomous LIN frame handling
  - Message buffer to store as many as 8 data bytes
  - Supports messages as long as 64 bytes
  - Detection and flagging of LIN errors (Sync field, delimiter, ID parity, bit framing, checksum and Time-out errors)
  - Classic or extended checksum calculation
  - Configurable break duration of up to 50-bit times
  - Programmable baud rate prescalers (13-bit mantissa, 4-bit fractional)
  - Diagnostic features (Loop back, LIN bus stuck dominant detection)
  - Interrupt driven operation with 16 interrupt sources
- LIN slave mode features
  - Autonomous LIN header handling
  - Autonomous LIN response handling
- UART mode
  - Full-duplex operation
  - Standard non return-to-zero (NRZ) mark/space format
  - Data buffers with 4-byte receive, 4-byte transmit
  - Configurable word length (8-bit, 9-bit, 16-bit, or 17-bit words)
  - Configurable parity scheme: none, odd, even, always 0
  - Speed as fast as 2 Mbit/s

Table 3. 144 LQFP pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
122	A[12]	SIUL	GPIO[12]	GPIO[12]
		DSPI_2	SOUT	—
		FlexPWM_0	A[2]	A[2]
		FlexPWM_0	B[2]	B[2]
		SIUL	—	EIRQ[11]
123	JCOMP	—	—	JCOMP
124	C[15]	SIUL	GPIO[47]	GPIO[47]
		FlexRay	CA_TR_EN	—
		eTimer_1	ETC[0]	ETC[0]
		FlexPWM_0	A[1]	A[1]
		CTU_0	—	EXT_IN
		FlexPWM_0	—	EXT_SYNC
125	D[0]	SIUL	GPIO[48]	GPIO[48]
		FlexRay	CA_TX	—
		eTimer_1	ETC[1]	ETC[1]
		FlexPWM_0	B[1]	B[1]
126	$V_{DD\_HV\_IO}$	—		
127	$V_{SS\_HV\_IO}$	—		
128	D[3]	SIUL	GPIO[51]	GPIO[51]
		FlexRay	CB_TX	—
		eTimer_1	ETC[4]	ETC[4]
		FlexPWM_0	A[3]	A[3]
129	D[4]	SIUL	GPIO[52]	GPIO[52]
		FlexRay	CB_TR_EN	—
		eTimer_1	ETC[5]	ETC[5]
		FlexPWM_0	B[3]	B[3]
130	$V_{DD\_HV\_REG\_2}$	—		
131	$V_{DD\_LV\_COR}$	—		
132	$V_{SS\_LV\_COR}$	—		
133	F[0]	SIUL	GPIO[80]	GPIO[80]
		FlexPWM_0	A[1]	A[1]
		eTimer_0	—	ETC[2]
		SIUL	—	EIRQ[28]

Table 4. 257 MAPBGA pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
C2	Not connected	—		
C3	$V_{SS\_HV\_IO\_RING}$	—		
C4	FCCU_F[1]	FCCU	F[1]	F[1]
C5	D[2]	SIUL	GPIO[50]	GPIO[50]
		eTimer_1	ETC[3]	ETC[3]
		FlexPWM_0	X[3]	X[3]
		FlexRay	—	CB_RX
C6	A[13]	SIUL	GPIO[13]	GPIO[13]
		FlexPWM_0	B[2]	B[2]
		DSPI_2	—	SIN
		FlexPWM_0	—	FAULT[0]
		SIUL	—	EIRQ[12]
C7	$V_{DD\_HV\_REG\_2}$	—		
C8	$V_{DD\_HV\_REG\_2}$	—		
C9	I[0]	SIUL	GPIO[128]	GPIO[128]
		eTimer_2	ETC[0]	ETC[0]
		DSPI_0	CS4	—
		FlexPWM_1	—	FAULT[0]
C10	JCOMP	—	—	JCOMP
C11	H[11]	SIUL	GPIO[123]	GPIO[123]
		FlexPWM_1	A[2]	A[2]
C12	I[1]	SIUL	GPIO[129]	GPIO[129]
		eTimer_2	ETC[1]	ETC[1]
		DSPI_0	CS5	—
		FlexPWM_1	—	FAULT[1]
C13	F[14]	SIUL	GPIO[94]	GPIO[94]
		LINFlexD_1	TXD	—
C14	B[1]	SIUL	GPIO[17]	GPIO[17]
		eTimer_1	ETC[3]	ETC[3]
		SSCM	DEBUG[1]	—
		FlexCAN_0	—	RXD
		FlexCAN_1	—	RXD
		SIUL	—	EIRQ[16]
C15	$V_{SS\_HV\_IO\_RING}$	—		

Table 4. 257 MAPBGA pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
M4	Not connected	—		
M6	V_{DD_LV}	—		
M7	V_{DD_LV}	—		
M8	V_{DD_LV}	—		
M9	V_{DD_LV}	—		
M10	V_{DD_LV}	—		
M11	V_{DD_LV}	—		
M12	V_{DD_LV}	—		
M14	C[11]	SIUL	GPIO[43]	GPIO[43]
		eTimer_0	ETC[4]	ETC[4]
		DSPI_2	CS2	—
M15	B[5]	SIUL	GPIO[21]	GPIO[21]
		JTAGC	—	TDI
M16	TMS	—		
M17	H[5]	SIUL	GPIO[117]	GPIO[117]
		FlexPWM_1	A[0]	A[0]
		DSPI_0	CS4	—
N1	XTAL	—		
N2	$V_{SS\_HV\_IO\_RING}$	—		
N3	D[5]	SIUL	GPIO[53]	GPIO[53]
		DSPI_0	CS3	—
		FlexPWM_0	—	FAULT[2]
N4	$V_{SS\_LV\_PLL0\_PLL1}$	—		
N14	Not connected	—		
N15	C[12]	SIUL	GPIO[44]	GPIO[44]
		eTimer_0	ETC[5]	ETC[5]
		DSPI_2	CS3	—
N16	A[2]	SIUL	GPIO[2]	GPIO[2]
		eTimer_0	ETC[2]	ETC[2]
		FlexPWM_0	A[3]	A[3]
		DSPI_2	—	SIN
		MC_RGM	—	ABS[0]
		SIUL	—	EIRQ[2]

Table 4. 257 MAPBGA pin function summary (continued)

Pin #	Port/function	Peripheral	Output function	Input function
R16	D[11]	SIUL	GPIO[59]	GPIO[59]
		FlexPWM_0	B[0]	B[0]
		eTimer_0	—	ETC[1]
R17	G[9]	SIUL	GPIO[105]	GPIO[105]
		FlexRay	DBG1	—
		DSPI_1	CS1	—
		FlexPWM_0	—	FAULT[1]
		SIUL	—	EIRQ[29]
T1	$V_{SS\_HV\_IO\_RING}$	—		
T2	$V_{DD\_HV\_IO\_RING}$	—		
T3	Not connected	—		
T4	C[1]	SIUL	—	GPIO[33]
		ADC_0	—	AN[2]
T5	E[5]	SIUL	—	GPIO[69]
		ADC_0	—	AN[8]
T6	E[7]	SIUL	—	GPIO[71]
		ADC_0	—	AN[6]
T7	$V_{SS\_HV\_ADR0}$	—		
T8	B[11]	SIUL	—	GPIO[27]
		ADC_0 ADC_1	—	AN[13]
T9	$V_{SS\_HV\_ADR1}$	—		
T10	E[9]	SIUL	—	GPIO[73]
		ADC_1	—	AN[7]
T11	E[10]	SIUL	—	GPIO[74]
		ADC_1	—	AN[8]
T12	E[12]	SIUL	—	GPIO[76]
		ADC_1	—	AN[6]
T13	E[0]	SIUL	—	GPIO[64]
		ADC_1	—	AN[5]
T14	A[0]	SIUL	GPIO[0]	GPIO[0]
		eTimer_0	ETC[0]	ETC[0]
		DSPI_2	SCK	SCK
		SIUL	—	EIRQ[0]

Table 7. Pin muxing (continued)

Port name	PCR	Peripheral	Alternate output function	Output mux sel	Input functions	Input mux select	Weak pull config during reset	Pad speed[1]		Pin #		
								SRC = 1	SRC = 0		144 pkg	257 pkg
G[3]	PCR[99]	SIUL	GPIO[99]	ALT0	GPIO[99]	—	—	M	S		104	D17
		FlexPWM_0	A[2]	ALT1	A[2]	PSMI[22]; PADSEL=2						
		eTimer_0	—	—	ETC[4]	PSMI[7]; PADSEL=3						
G[4]	PCR[100]	SIUL	GPIO[100]	ALT0	GPIO[100]	—	—	M	S		100	F17
		FlexPWM_0	B[2]	ALT1	B[2]	PSMI[26]; PADSEL=2						
		eTimer_0	—	—	ETC[5]	PSMI[8]; PADSEL=3						
G[5]	PCR[101]	SIUL	GPIO[101]	ALT0	GPIO[101]	—	—	M	S		85	N17
		FlexPWM_0	X[3]	ALT1	X[3]	PSMI[30]; PADSEL=2						
		DSPI_2	CS3	ALT2	—	—						
G[6]	PCR[102]	SIUL	GPIO[102]	ALT0	GPIO[102]	—	—	M	S		98	G17
		FlexPWM_0	A[3]	ALT1	A[3]	PSMI[23]; PADSEL=3						
G[7]	PCR[103]	SIUL	GPIO[103]	ALT0	GPIO[103]		—	M	S		83	P17
		FlexPWM_0	B[3]	ALT1	B[3]	PSMI[27]; PADSEL=3						
G[8]	PCR[104]	SIUL	GPIO[104]	ALT0	GPIO[104]	—	—	M	S		81	P16
		FlexRay	DBG0	ALT1	—	—						
		DSPI_0	CS1	ALT2	—	—						
		FlexPWM_0	—	—	FAULT[0]	PSMI[16]; PADSEL=2						
		SIUL	—	—	EIRQ[21]	—						

Table 7. Pin muxing (continued)

Port name	PCR	Peripheral	Alternate output function	Output mux sel	Input functions	Input mux select	Weak pull config during reset	Pad speed[1]		Pin #		
								SRC = 1	SRC = 0		144 pkg	257 pkg
G[9]	PCR[105]	SIUL	GPIO[105]	ALT0	GPIO[105]	—	—	M	S		79	R17
		FlexRay	DBG1	ALT1	—	—						
		DSPI_1	CS1	ALT2	—	—						
		FlexPWM_0	—	—	FAULT[1]	PSMI[17]; PADSEL=2						
		SIUL	—	—	EIRQ[29]	—						
G[10]	PCR[106]	SIUL	GPIO[106]	ALT0	GPIO[106]	—	—	M	S		77	P15
		FlexRay	DBG2	ALT1	—	—						
		DSPI_2	CS3	ALT2	—	—						
		FlexPWM_0	—	—	FAULT[2]	PSMI[18]; PADSEL=1						
G[11]	PCR[107]	SIUL	GPIO[107]	ALT0	GPIO[107]	—	—	M	S		75	U15
		FlexRay	DBG3	ALT1	—	—						
		FlexPWM_0	—	—	FAULT[3]	PSMI[19]; PADSEL=2						
G[12]	PCR[108]	SIUL	GPIO[108]	ALT0	GPIO[108]	—	—	F	S		—	F2
		NPC	MDO[11]	ALT2	—	—						
G[13]	PCR[109]	SIUL	GPIO[109]	ALT0	GPIO[109]	—	—	F	S		—	H1
		NPC	MDO[10]	ALT2	—	—						
G[14]	PCR[110]	SIUL	GPIO[110]	ALT0	GPIO[110]	—	—	F	S		—	A6
		NPC	MDO[9]	ALT2	—	—						
G[15]	PCR[111]	SIUL	GPIO[111]	ALT0	GPIO[111]	—	—	F	S		—	J2
		NPC	MDO[8]	ALT2	—	—						
Port H												
H[0]	PCR[112]	SIUL	GPIO[112]	ALT0	GPIO[112]	—	—	F	S		—	A5
		NPC	MDO[7]	ALT2	—	—						

Table 7. Pin muxing (continued)

Port name	PCR	Peripheral	Alternate output function	Output mux sel	Input functions	Input mux select	Weak pull config during reset	Pad speed[1]		Pin #		
								SRC = 1	SRC = 0		144 pkg	257 pkg
H[1]	PCR[113]	SIUL	GPIO[113]	ALT0	GPIO[113]	—	—	F	S		—	F1
		NPC	MDO[6]	ALT2	—	—						
H[2]	PCR[114]	SIUL	GPIO[114]	ALT0	GPIO[114]	—	—	F	S		—	A4
		NPC	MDO[5]	ALT2	—	—						
H[3]	PCR[115]	SIUL	GPIO[115]	ALT0	GPIO[115]	—	—	F	S		—	G1
		NPC	MDO[4]	ALT2	—	—						
H[4]	PCR[116]	SIUL	GPIO[116]	ALT0	GPIO[116]	—	—	M	S		—	L16
		FlexPWM_1	X[0]	ALT1	X[0]	—						
		eTimer_2	ETC[0]	ALT2	ETC[0]	PSMI[39]; PADSEL=0						
H[5]	PCR[117]	SIUL	GPIO[117]	ALT0	GPIO[117]	—	—	M	S		—	M17
		FlexPWM_1	A[0]	ALT1	A[0]	—						
		DSPI_0	CS4	ALT3	—	—						
H[6]	PCR[118]	SIUL	GPIO[118]	ALT0	GPIO[118]	—	—	M	S		—	H17
		FlexPWM_1	B[0]	ALT1	B[0]	—						
		DSPI_0	CS5	ALT3	—	—						
H[7]	PCR[119]	SIUL	GPIO[119]	ALT0	GPIO[119]	—	—	M	S		—	K16
		FlexPWM_1	X[1]	ALT1	X[1]	—						
		eTimer_2	ETC[1]	ALT2	ETC[1]	PSMI[40]; PADSEL=0						
H[8]	PCR[120]	SIUL	GPIO[120]	ALT0	GPIO[120]	—	—	M	S		—	K15
		FlexPWM_1	A[1]	ALT1	A[1]	—						
		DSPI_0	CS6	ALT3	—	—						
H[9]	PCR[121]	SIUL	GPIO[121]	ALT0	GPIO[121]	—	—	M	S		—	G16
		FlexPWM_1	B[1]	ALT1	B[1]	—						
		DSPI_0	CS7	ALT3	—	—						

Table 8. Absolute maximum ratings[1] (continued)

Symbol		Parameter	Conditions	Min	Max	Unit
TV_{DD}	SR	Supply ramp rate	—	3.0×10^{-6} (3.0 V/sec)	0.5 V/µs	V/µs
V_{IN}	SR	Voltage on any pin with respect to ground ($V_{SS\_HV\_IOx}$)	—	–0.3	6.0[5]	V
			Relative to V_{DD}	–0.3	V_{DD} + 0.3[5,6]	
I_{INJPAD}	SR	Injected input current on any pin during overload condition	—	–10	10	mA
I_{INJSUM}	SR	Absolute sum of all injected input currents during overload condition	—	–50	50	mA
T_{STG}	SR	Storage temperature	—	–55	150	°C

1 Functional operating conditions are given in the DC electrical characteristics. Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond the listed maxima may affect device reliability or cause permanent damage to the device.

2 5.3 V for 10 hours cumulative over lifetime of device, 3.3 V +10% for time remaining.

3 Voltage overshoots during a high-to-low or low-to-high transition must not exceed 10 seconds per instance.

4 6.4 V for 10 hours cumulative time, 6.0 V for time remaining.

5 Internal structures hold the input voltage less than the maximum voltage on all pads powered by VDDE supplies, if the maximum injection current specification is met and VDDE is within the operating voltage specifications.

6 Only when V_{DD} < 5.2 V.

3.3 Recommended operating conditions

Table 9. Recommended operating conditions (3.3 V)

Symbol		Parameter	Conditions	Min[1]	Max	Unit
$V_{DD\_HV\_REG}$	SR	3.3 V voltage regulator supply voltage	—	3.0	3.63	V
$V_{DD\_HV\_IOx}$	SR	3.3 V input/output supply voltage	—	3.0	3.63	V
$V_{SS\_HV\_IOx}$	SR	Input/output ground voltage	—	0	0	V
$V_{DD\_HV\_FLA}$	SR	3.3 V flash supply voltage	—	3.0	3.63	V
$V_{SS\_HV\_FLA}$	SR	Flash memory ground	—	0	0	V
$V_{DD\_HV\_OSC}$	SR	3.3 V crystal oscillator amplifier supply voltage	—	3.0	3.63	V
$V_{SS\_HV\_OSC}$	SR	3.3 V crystal oscillator amplifier reference voltage	—	0	0	V
$V_{DD\_HV\_ADR0}$[2,3] $V_{DD\_HV\_ADR1}$	SR	3.3 V / 5.0 V ADC_0 high reference voltage 3.3 V / 5.0 V ADC_1 high reference voltage	—	4.5 to 5.5 or 3.0 to 3.63		V
$V_{DD\_HV\_ADV}$	SR	3.3 V ADC supply voltage	—	3.0	3.63	V
$V_{SS\_HV\_AD0}$ $V_{SS\_HV\_AD1}$	SR	ADC_0 ground and low reference voltage ADC_1 ground and low reference voltage	—	0	0	V
$V_{SS\_HV\_ADV}$	SR	3.3 V ADC supply ground	—	0	0	V
$V_{DD\_LV\_REGCOR}$[4]	SR	Internal supply voltage	—	—	—	V
$V_{SS\_LV\_REGCOR}$[5]	SR	Internal reference voltage	—	0	0	V
$V_{DD\_LV\_CORx}$[2]	SR	Internal supply voltage	—	—	—	V

3.4.1 General notes for specifications at maximum junction temperature

An estimation of the chip junction temperature, T_J, can be obtained from Equation 1:

$$T_J = T_A + (R_{\theta JA} \times P_D) \quad \textit{Eqn. 1}$$

where:

T_A = ambient temperature for the package (^oC)
$R_{\theta JA}$ = junction to ambient thermal resistance ($^oC/W$)
P_D = power dissipation in the package (W)

The junction to ambient thermal resistance is an industry standard value that provides a quick and easy estimation of thermal performance. Unfortunately, there are two values in common usage: the value determined on a single layer board and the value obtained on a board with two planes. For packages such as the PBGA, these values can be different by a factor of two. Which value is closer to the application depends on the power dissipated by other components on the board. The value obtained on a single layer board is appropriate for the tightly packed printed circuit board. The value obtained on the board with the internal planes is usually appropriate if the board has low power dissipation and the components are well separated.

When a heat sink is used, the thermal resistance is expressed in Equation 2 as the sum of a junction to case thermal resistance and a case to ambient thermal resistance:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CA} \quad \textit{Eqn. 2}$$

where:

$R_{\theta JA}$ = junction to ambient thermal resistance (°C/W)
$R_{\theta JC}$ = junction to case thermal resistance (°C/W)
$R_{\theta CA}$ = case to ambient thermal resistance (°C/W)

$R_{\theta JC}$ is device related and cannot be influenced by the user. The user controls the thermal environment to change the case to ambient thermal resistance, $R_{\theta CA}$. For instance, the user can change the size of the heat sink, the air flow around the device, the interface material, the mounting arrangement on printed circuit board, or change the thermal dissipation on the printed circuit board surrounding the device.

To determine the junction temperature of the device in the application when heat sinks are not used, the Thermal Characterization Parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using Equation 3:

$$T_J = T_T + (\Psi_{JT} \times P_D) \quad \textit{Eqn. 3}$$

where:

T_T = thermocouple temperature on top of the package (°C)
Ψ_{JT} = thermal characterization parameter (°C/W)
P_D = power dissipation in the package (W)

The thermal characterization parameter is measured per JESD51-2 specification using a 40 gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1 mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

3.4.1.1 References

Semiconductor Equipment and Materials International
3081 Zanker Road

Table 19. DC electrical characteristics[1] (continued)

Symbol		Parameter	Conditions	Min	Typ	Max	Unit
V_{OH_M}	P	Medium, high level output voltage	I_{OH} = –2 mA	$V_{DD\_HV\_IOx}$ – 0.8	—	—	V
V_{OL_F}	P	Fast, high level output voltage	I_{OL} = 11 mA	—	—	0.5	V
V_{OH_F}	P	Fast, high level output voltage	I_{OH} = –11 mA	$V_{DD\_HV\_IOx}$ – 0.8	—	—	V
V_{OL_SYM}	P	Symmetric, high level output voltage	I_{OL} = 1.5 mA	—	—	0.5	V
V_{OH_SYM}	P	Symmetric, high level output voltage	I_{OH} = –1.5 mA	$V_{DD\_HV\_IOx}$ – 0.8	—	—	V
I_{INJ}	T	DC injection current per pin (all bi-directional ports)	—	–1	—	1	mA
I_{PU}	P	Equivalent pull-up current	$V_{IN} = V_{IL}$	–130	—	—	µA
			$V_{IN} = V_{IH}$	—	—	–10	
I_{PD}	P	Equivalent pull-down current	$V_{IN} = V_{IL}$	10	—	—	µA
			$V_{IN} = V_{IH}$	—	—	130	
I_{IL}	P	Input leakage current (all bidirectional ports)	T_J = –40 to +150 °C	-1	—	1	µA
		Input leakage current (all ADC input-only ports)[4]		-0.25	—	0.25	
		Input leakage current (shared ADC input-only ports)		-0.3	—	0.3	
V_{ILR}	P	$\overline{\text{RESET}}$, low level input voltage	—	–0.1[2]	—	0.35 $V_{DD\_HV\_IOx}$	V
V_{IHR}	P	$\overline{\text{RESET}}$, high level input voltage	—	0.65 $V_{DD\_HV\_IOx}$	—	$V_{DD\_HV\_IOx}$+0.1[2]	V
V_{HYSR}	D	$\overline{\text{RESET}}$, Schmitt trigger hysteresis	—	0.1 $V_{DD\_HV\_IOx}$	—	—	V
V_{OLR}	D	$\overline{\text{RESET}}$, low level output voltage	I_{OL} = 2 mA	—	—	0.5	V
I_{PD}	D	$\overline{\text{RESET}}$, equivalent pull-down current	$V_{IN} = V_{IL}$	10	—	—	µA
			$V_{IN} = V_{IH}$	—	—	130	

1 These specifications are design targets and subject to change per device characterization.

2 “SR” parameter values must not exceed the absolute maximum ratings shown in Table 8.

3 The max input voltage on the ADC pins is the ADC reference voltage VDD_HV_ADRx.

4 Measured values are applicable to all modes of the pad i.e. IBE = 0/1 and / or APC= 0/1.

3.10 Supply current characteristics

Current consumption data is given in Table 20. These specifications are design targets and are subject to change per device characterization.

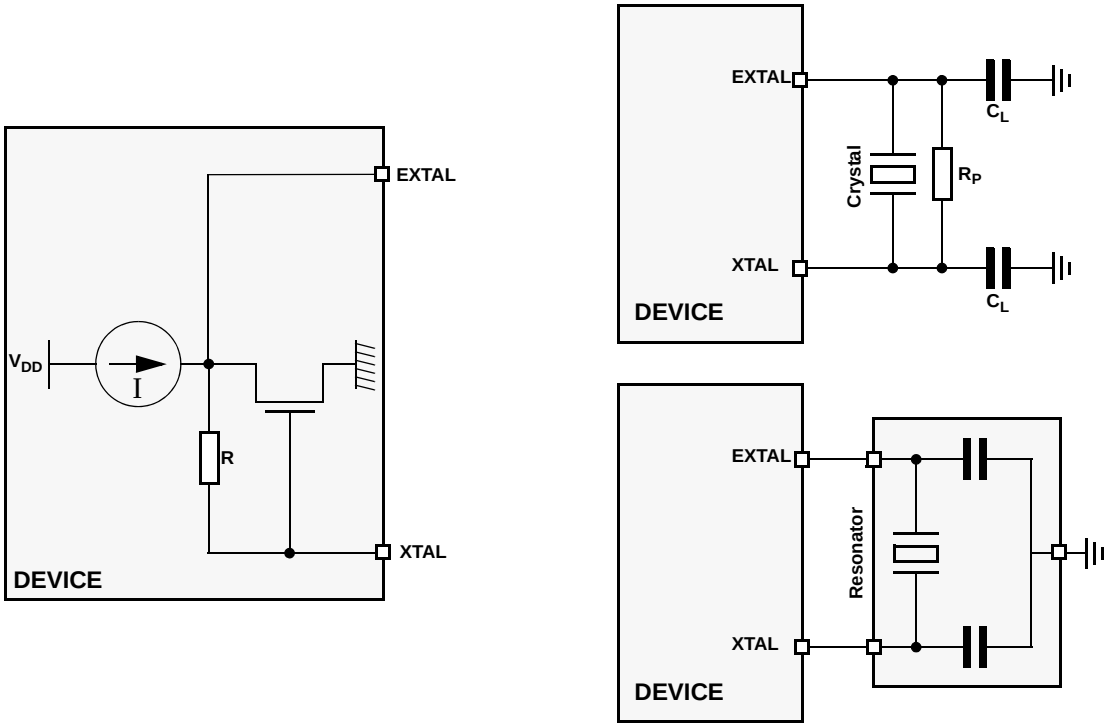


Figure 5. Crystal oscillator and resonator connection scheme

NOTE

XTAL/EXTAL must not be directly used to drive external circuits.

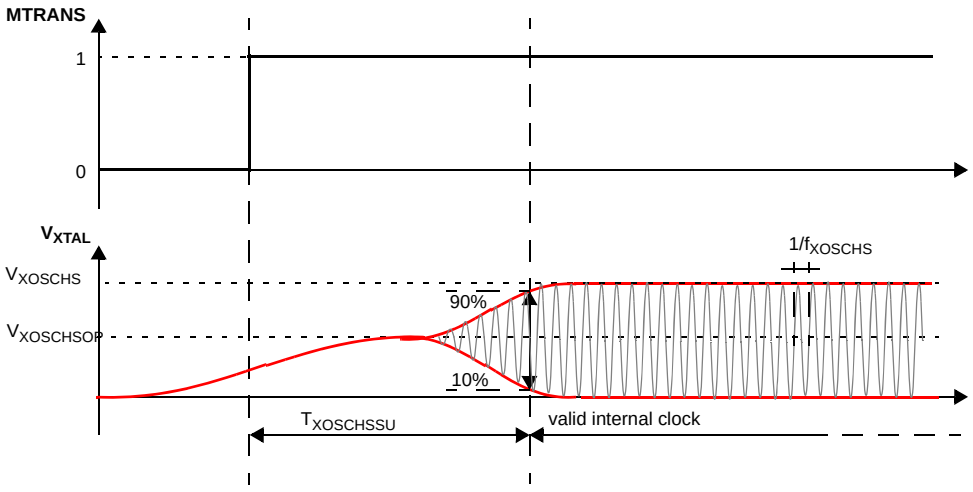


Figure 6. Main oscillator electrical characteristics

Of course, R_L shall be sized also according to the current limitation constraints, in combination with R_S (source impedance) and R_F (filter resistance). Being C_F definitively bigger than C_{P1}, C_{P2} and C_S, then the final voltage V_{A2} (at the end of the charge transfer transient) will be much higher than V_{A1}. Equation 10 must be respected (charge balance assuming now C_S already charged at V_{A1}):

$$V_{A2} \bullet (C_S + C_{P1} + C_{P2} + C_F) = V_A \bullet C_F + V_{A1} \bullet (C_{P1} + C_{P2} + C_S) \quad \textit{Eqn. 10}$$

The two transients above are not influenced by the voltage source that, due to the presence of the R_FC_F filter, is not able to provide the extra charge to compensate the voltage drop on C_S with respect to the ideal source V_A; the time constant R_FC_F of the filter is very high with respect to the sampling time (T_S). The filter is typically designed to act as anti-aliasing.

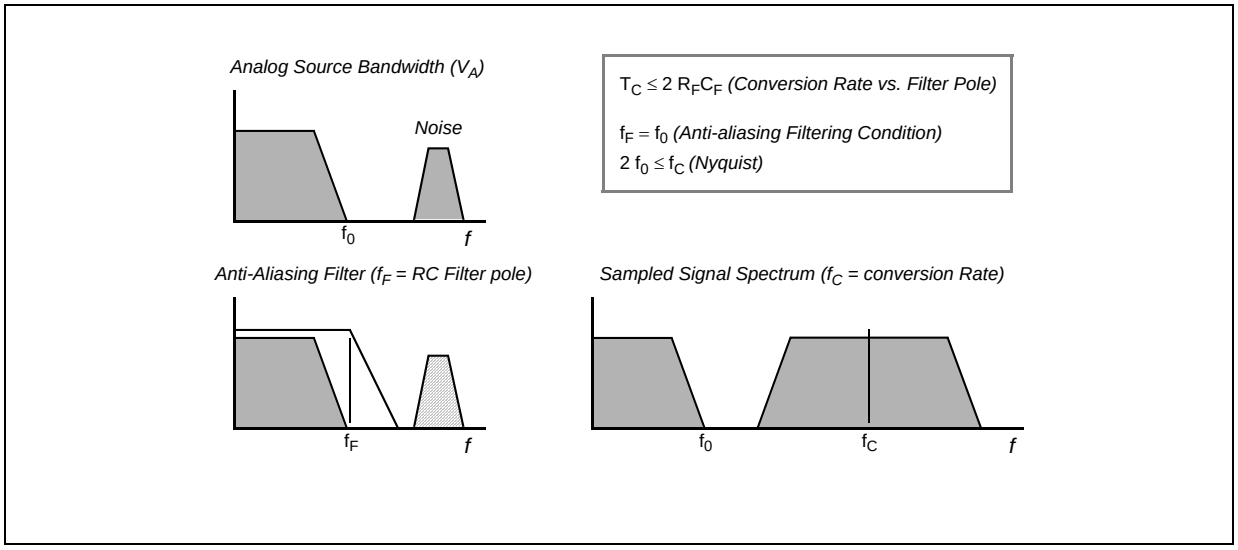


Figure 10. Spectral representation of input signal

Calling f_0 the bandwidth of the source signal (and as a consequence the cut-off frequency of the anti-aliasing filter, f_F), according to the Nyquist theorem the conversion rate f_C must be at least $2f_0$; it means that the constant time of the filter is greater than or at least equal to twice the conversion period (T_C). Again the conversion period T_C is longer than the sampling time T_S, which is just a portion of it, even when fixed channel continuous conversion mode is selected (fastest conversion rate at a specific channel): in conclusion it is evident that the time constant of the filter R_FC_F is definitively much higher than the sampling time T_S, so the charge level on C_S cannot be modified by the analog signal source during the time in which the sampling switch is closed.

The considerations above lead to impose new constraints on the external circuit, to reduce the accuracy error due to the voltage drop on C_S; from the two charge balance equations above, it is simple to derive Equation 11 between the ideal and real sampled voltage on C_S:

Eqn. 11

$$\frac{V_{A2}}{V_A} = \frac{C_{P1} + C_{P2} + C_F}{C_{P1} + C_{P2} + C_F + C_S}$$

From this formula, in the worst case (when V_A is maximum, that is for instance 5 V), assuming to accept a maximum error of half a count, a constraint is evident on C_F value:

Eqn. 12

$$C_F > 8192 \bullet C_S$$

4 During the sample time the input capacitance CS can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach its final voltage level within t_{sample}. After the end of the sample time t_{sample}, changes of the analog input voltage have no effect on the conversion result. Values for the sample clock t_{sample} depend on programming.

5 This parameter does not include the sample time Tsample, but only the time for determining the digital result.

6 See Figure 8.

7 For the 144-pin package

8 No missing codes

3.16 Flash memory electrical characteristics

Table 26. Flash memory program and erase electrical specifications

No.	Symbol		Parameter	Typ[1]	Initial Max[2]	Lifetime Max[3]	Unit
1	$T_{DWPROGRAM}$	*[4]	Double word (64 bits) program time[4]	30	—	500	µs
2	$T_{PPROGRAM}$	*4	Page(128 bits) program time[4]	40	160	500	µs
3	$T_{16KPPERASE}$	*4	16 KB block pre-program and erase time	250	1000	5000	ms
4	$T_{48KPPERASE}$	*4	48 KB block pre-program and erase time	400	1500	5000	ms
5	$T_{64KPPERASE}$	*4	64 KB block pre-program and erase time	450	1800	5000	ms
6	$T_{128KPPERASE}$	*4	128 KB block pre-program and erase time	800	2600	7500	ms
7	$T_{256KPPERASE}$	*4	256 KB block pre-program and erase time	1400	5200	15000	ms

1 Typical program and erase times represent the median performance and assume nominal supply values and operation at 25C. These values are characterized, but not tested.I

2 Initial Max program and erase times provide guidance for time-out limits used in the factory and apply for <100 program/erase cycles, nominal supply values and operation at 25C. These values are verified at production test.

3 Lifetime Max program and erase times apply across the voltage, temperature, and cycling range of product life. These values are characterized, but not tested.

4 Program times are actual hardware programming times and do not include software overhead.

Table 27. Flash memory timing

Symbol		Parameter	Value			Unit
			Min	Typ	Max	
T_{RES}	D	Time from clearing the MCR-ESUS or PSUS bit with EHV = 1 until DONE goes low	—	—	100	ns
T_{DONE}	D	Time from 0 to 1 transition on the MCR-EHV bit initiating a program/erase until the MCR-DONE bit is cleared	—	—	5	ns
T_{PSRT}	D	Time between program suspend resume and the next program suspend request.[1]	100	—	—	µs
T_{ESRT}	D	Time between erase suspend resume and the next erase suspend request.[2]	10			ms

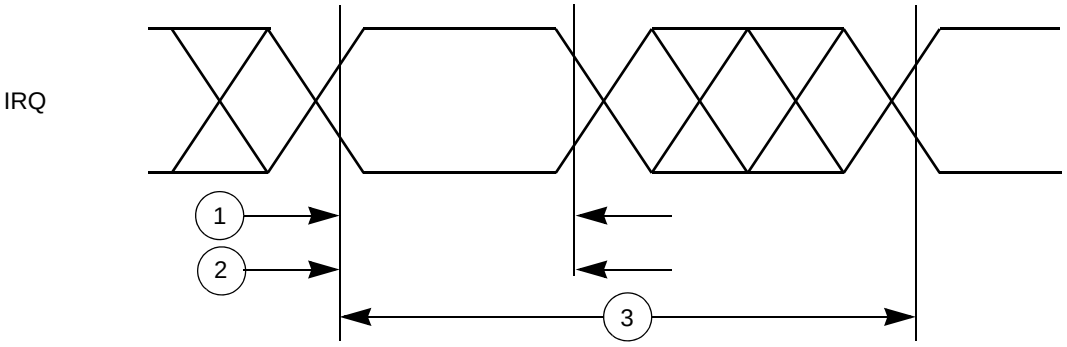
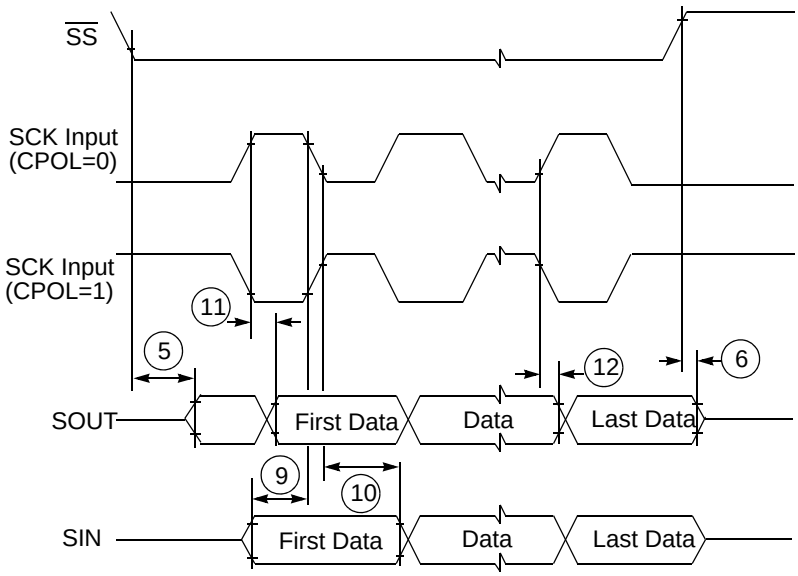


Figure 29. External interrupt timing

3.20.6 DSPI timing

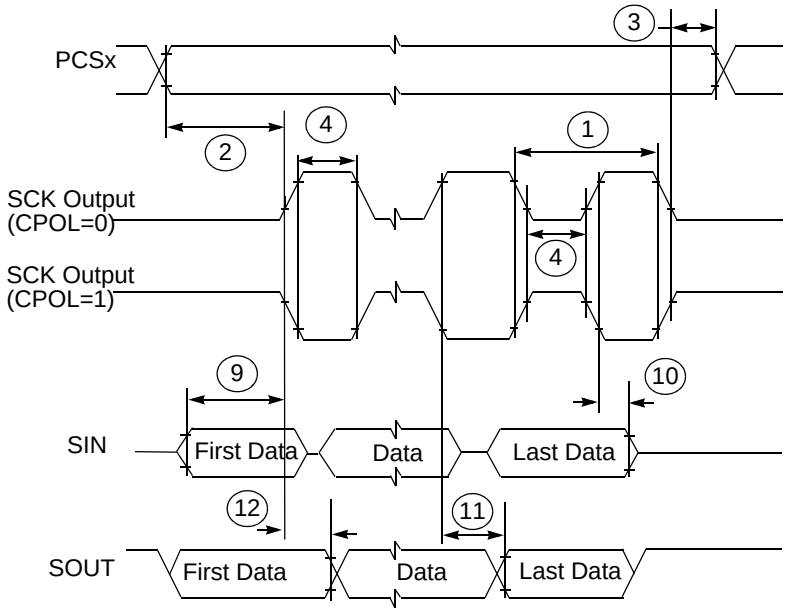
Table 39. DSPI timing

No.	Symbol		Parameter	Conditions	Min	Max	Unit
1	t_{SCK}	D	DSPI cycle time	Master (MTFE = 0)	62	—	ns
		D		Slave (MTFE = 0)	62	—	
		D		Slave Receive Only Mode[1]	16	—	
2	t_{CSC}	D	PCS to SCK delay	—	16	—	ns
3	t_{ASC}	D	After SCK delay	—	16	—	ns
4	t_{SDC}	D	SCK duty cycle	—	t_{SCK}/2 - 10	t_{SCK}/2 + 10	ns
5	t_A	D	Slave access time	$\overline{SS}$ active to SOUT valid	—	40	ns
6	t_{DIS}	D	Slave SOUT disable time	$\overline{SS}$ inactive to SOUT High-Z or invalid	—	10	ns
7	t_{PCSC}	D	PCSx to $\overline{PCSS}$ time	—	13	—	ns
8	t_{PASC}	D	$\overline{PCSS}$ to PCSx time	—	13	—	ns
9	t_{SUI}	D	Data setup time for inputs	Master (MTFE = 0)	20	—	ns
				Slave	2	—	
				Master (MTFE = 1, CPHA = 0)	5	—	
				Master (MTFE = 1, CPHA = 1)	20	—	
10	t_{HI}	D	Data hold time for inputs	Master (MTFE = 0)	–5	—	ns
				Slave	4	—	
				Master (MTFE = 1, CPHA = 0)	11	—	
				Master (MTFE = 1, CPHA = 1)	–5	—	
11	t_{SUO}	D	Data valid (after SCK edge)	Master (MTFE = 0)	—	4	ns
				Slave	—	23	
				Master (MTFE = 1, CPHA = 0)	—	12	
				Master (MTFE = 1, CPHA = 1)	—	4	



Note: The numbers shown are referenced in Table 39.

Figure 33. DSPI classic SPI timing — slave, CPHA = 1



Note: The numbers shown are referenced in Table 39.

Figure 34. DSPI modified transfer format timing — master, CPHA = 0

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

TITLE: PBGA, LOW PROFILE, FINE PITCH, 257 I/O, 14 X 14 PKG, 0.8 MM PITCH (MAP)	CASE NUMBER: 2082–01
	STANDARD: JEDEC MO–275A–JJAC–1
	PACKAGE CODE: IN AGILE | SHEET: 2

Figure 42. 257 MAPBGA package mechanical drawing (2 of 2)

Table 41. Revision history (continued)

Revision	Date	Description of changes
6 (cont.)	11 Mar 2011 (cont.)	Added “WKUP/NMI Timing” subsection and “WKUP/NMI Glitch Filter” table to the “AC timing characteristics” section. Added “Nexus DDR Mode output timing” table to the “Nexus timing” section. Removed the “CLKOUT” diagram from the “External interrupt timing (IRQ pin)” section as it is not relevant. Corrected an error in the IRQ timing in the “External interrupt timing” figure. Updated the t_{SDC} parameters in the “DSPI timing” table. Renamed the “Electromagnetic Interference (EMI) characteristics” section (is “Electromagnetic Interference (EMI) characteristics (cut1)”) and revised all information in that section. In the “Voltage regulator electrical characteristics” section, added the BCX68 from Infineon to the list of supported transistors. Revised the “Voltage regulator electrical specifications” table to include cut1 and cut2 information. Renamed the “Supply current characteristics” section (is “Supply current characteristics (cut2)”) and revised it to show meaningful data. In the footnotes of the “Main oscillator electrical characteristics” table, changed SELMARGIN to XOSC_MARGIN. In the “ADC conversion characteristics” table: • Changed “LSB” to “Counts”. • Created separate rows for the TUE specifications. Added bullet regarding HALT and STOP in the “Clock, reset, power, mode and test control modules (MC_CGM, MC_RGM, MC_PCU, and MC_ME)“ subsection of the “Features“ section. In the “Analog-to-Digital Converter module“ subsection of the “Feature Details” section, changed “Motor control mode“ to “CTU mode“ to be consistent with the nomenclature used in the Reference Manual. Updated the JCOMP entries in the “Pin function summary“ table. Added footnotes regarding pad pull devices to NMI, TMS, TCK, and JCOMP in the “System pins“ table. Added “Time constant of RC filter at LVD input” parameters to the “Main supply LVD (LVD Main) specifications“ table. In the “Supply current characteristics (cut2)“ table: • Changed “$I_{DD\_LV\_MAX}$” to “$I_{DD\_LV\_MAX}$“; • Removed all “40-120 MHz” frequency ranges from the “Conditions” column; • Updated the “Max” values column; • Added parameter “$I_{DD\_LV\_TYP}$ + $I_{DD\_LV\_PLL}$“ with “P” classification and special footnote; • Changed all “25°C“ temperature conditions to “ambient”; • Added “T_J = 150 °C“ condition to parameters $I_{DD\_HV\_ADC}$, $I_{DD\_HV\_AREF}$, $I_{DD\_HV\_OSC}$, and $I_{DD\_HV\_FLASH}$. Changed the timing diagram in the “Main oscillator electrical characteristics” section to reference MTRANS assertion instead of V_{DDMIN}. Updated the jitter specs in the “FMPLL electrical characteristics“ table. In the “ADC conversion characteristics“ table, changed all parameters with units of “counts” to units of “LSB” and updated Min/Max values. Changed $I_{DD\_LV\_BIST}$ + $I_{DD\_LV\_PLL}$ operating current (for both cases) to TBD. In the “Supply current characteristics (cut2)” section, added a footnote that $I_{DD\_HV\_ADC}$ and $I_{DD\_HV\_AREF}$ represent the total current of both ADCs in the “Current consumption characteristics” table.

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